

Abstract

Electroplating in device making. Development of technological process of applying tin-lead alloy for printed circuit boards.

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In this project the technology of application of coverage shiny tin-lead alloy from tetrafluorborate electrolyte with additives Limeda POS-1 and Syntanol DS-10 on printed circuit boards to provide high ability to brazing and protection of figure conductive from the action environment was developed. The technological process calculations were done for capacity of 105000 PCB / year.

The project envisaged measures for safety automation parameters of the coating, the proposed scheme of regeneration and recycling of electrolyte components for electroplating tin-lead alloy, the main technical and economic indicators were designed.

Keywords: applying tin-lead alloy, plating bath, the automatic line, current density, a current source, printed circuit board, tetrafluorborate electrolyte.

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